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Part Number: [0780610001](#)
Status: **Active**
Description: 1.00mm (.039") Pitch Fully Buffered DIMM Socket, Vertical, Through Hole, 0.38µm (15µ") Gold(Au) Selective Plating, 240 Circuits, with Beveled Metal Pins, with Off-White Latches, 2.67mm (.105") Solder Tail Length, Lead-free

Documents:

[3D Model](#) [Product Specification PS-78061-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR 19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [78061](#)
 Comments Latches in Off-White Color Solder Tail Length at 2.67mm (.105")
 Component Type Memory Module
 JEDEC Outline MO-256
 Product Name FB DIMM

Physical

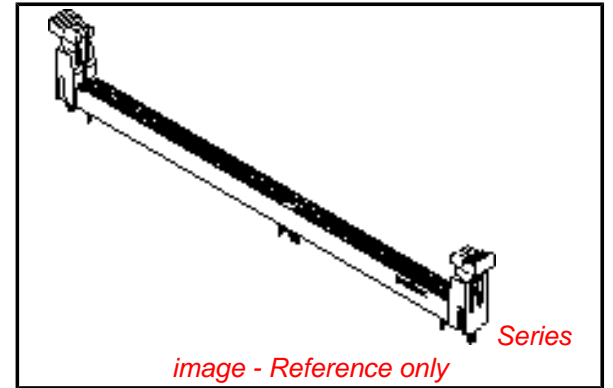
Circuits (Loaded) 240
 Color - Resin Black, Natural
 Durability (mating cycles max) 25
 Entry Angle Vertical (Top Entry)
 Flammability 94V-0
 Keying to Mating Part Yes
 Material - Metal Brass, Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin-Lead
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.105 In
 PC Tail Length (mm) 2.67 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.60 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Plating min: Mating (µin) 15
 Plating min: Mating (µm) 0.38
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
 Voltage - Maximum 30V
 Voltage Key 1.8V, Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
 Lead-free Process Capability SMC & Wave Capable (TH only)
 Max. Cycles at Max. Process Temperature 1



EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Halogen-Free Status

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[78061Series](#)

Mates With

JEDEC MO-256 modules

Process Temperature max. C

265

Material Info

Reference - Drawing Numbers

Product Specification

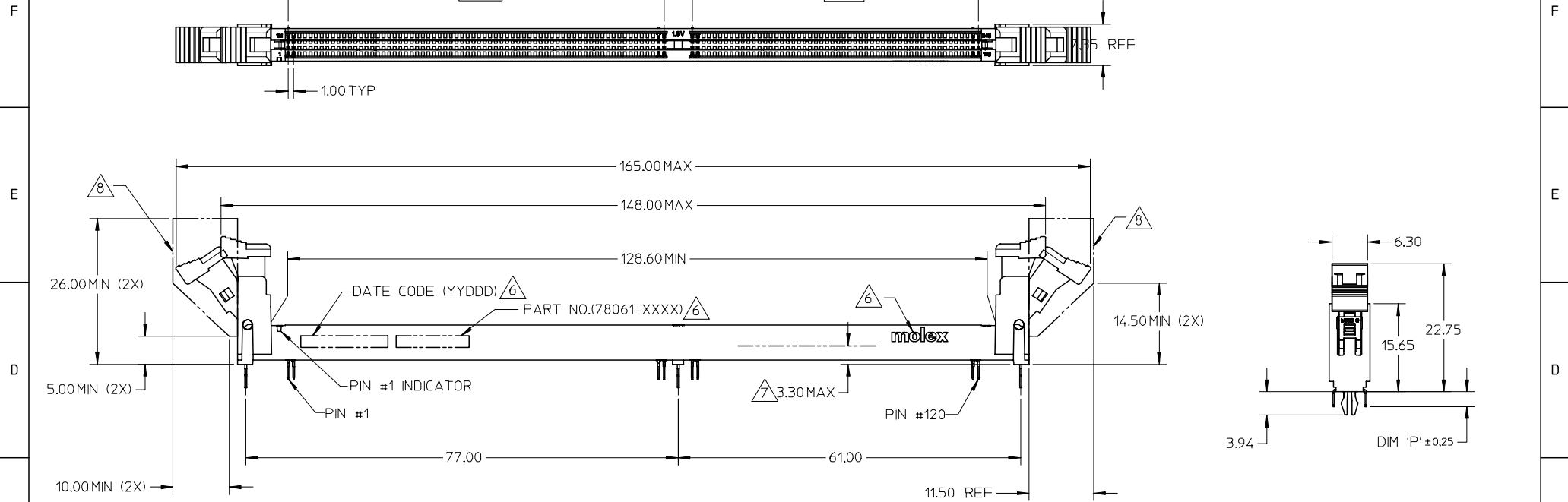
PS-78061-001, RPS-78061-001

Sales Drawing

SD-78061-001

This document was generated on 04/13/2010

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NOTES :

- MATERIAL : HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0
COLOUR : BLACK.
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOUR : NATURAL (OFF WHITE) OR BLACK.
TERMINAL : COPPER ALLOY.
- PLATING - SEE TABLE ON SHEET 4.
- CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS
(MEASURED FROM P.C. PADS).
- REFER TO PRODUCT SPECIFICATION, PS-78061-001 FOR PERFORMANCE SPECIFICATIONS.
- PRODUCT SHALL BE PACKED IN TRAY. PLS REFER TO SHEET 5.
- MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
- MODULE SEATING PLANE FROM TOP OF PCB.
- KEEP OUT ZONE RESERVED FOR LATCH (PER JEDEC SO-003,REV.A).
- MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.
- KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR
(INCLUDING LATCH) IS MOUNTED ON THE PCB
(PER JEDEC SO-003,REV.A).

TRAY DWG ADDED	2006/12/26
EC NO: S2007-0602	2006/12/26
DRWN:CMTED	2006/12/26
CHKD:SHLENI	2006/12/26
APPR:GGLLEE	2006/12/28
REV	DESCRIPTION
A4	

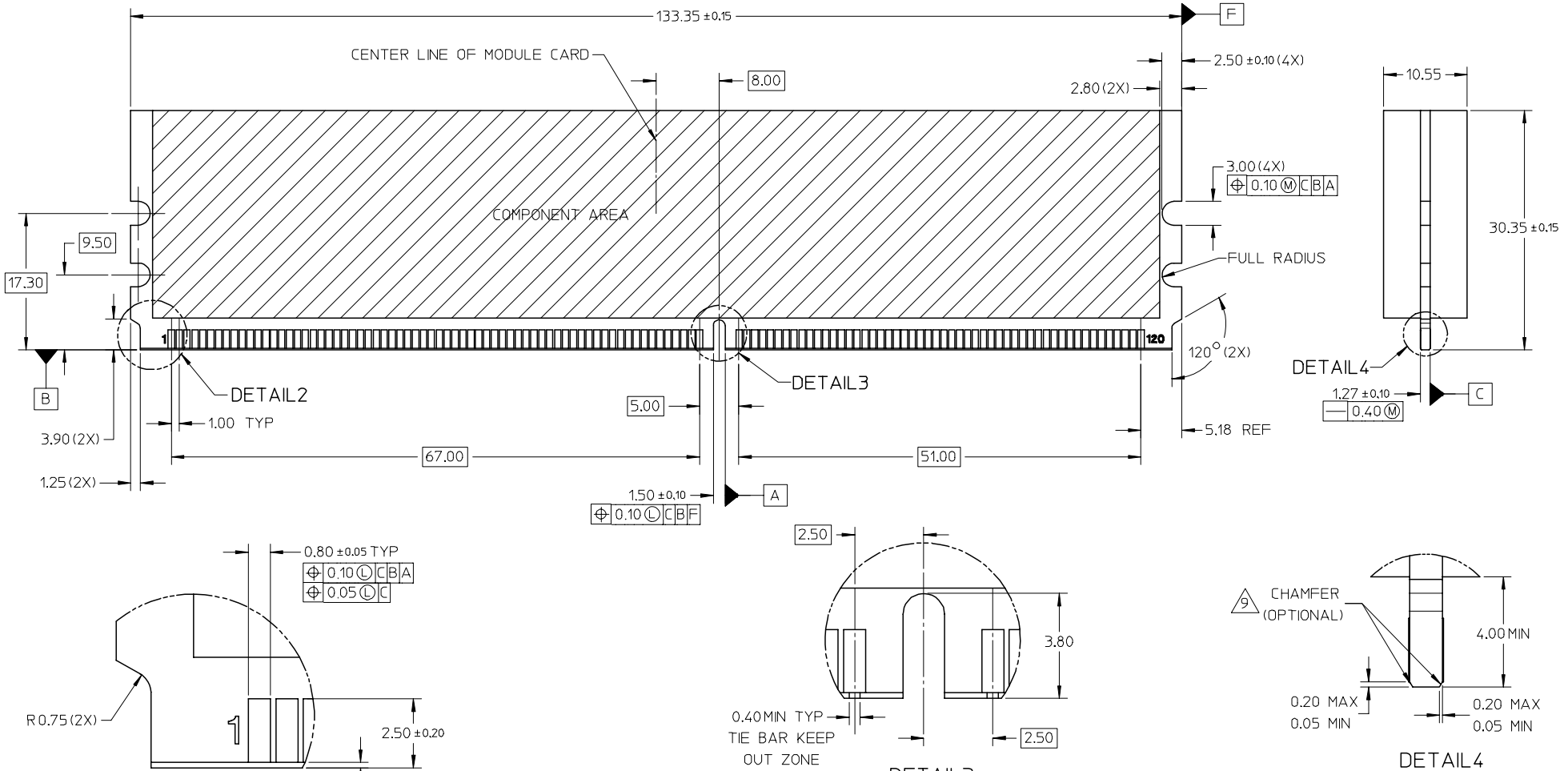
QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.2 ± ---
1 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
JTAN	2005/10/20
CHECKED BY	DATE
SRRAMESH	2005/12/05
APPROVED BY	DATE
GGLLEE	2005/12/06
MATERIAL NO.	
SEE TABLE	
SIZE	A3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
FB DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
MOLEX MOLEX INCORPORATED		SHEET NO. 1 OF 5
DOCUMENT NO. SD-78061-001		

MODULE CARD
 FB DIMM, DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (PER JEDEC MO-256 REV.C, DATE : 12/05)



DETAIL2

DETAIL3

DETAIL4

TRAY DWG ADDED EC NO: S2007-0602 DRWN:CMTEO 2006/12/26 CHKD:SHLENI 2006/12/26 APPR:GGLEE 2006/12/28	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DRAWN BY JTAN	DATE 2005/10/20	CHECKED BY SRRAMESH	DATE 2005/12/05	TITLE FB DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
	APPROVED BY GGLEE	DATE 2005/12/06	MOLEX MOLEX INCORPORATED			SHEET NO. 2 OF 5	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78061-001			

F

F

E

E

D

D

C

C

B

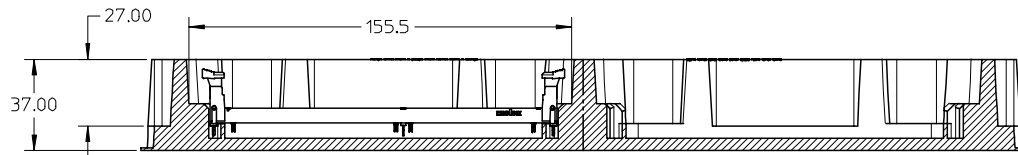
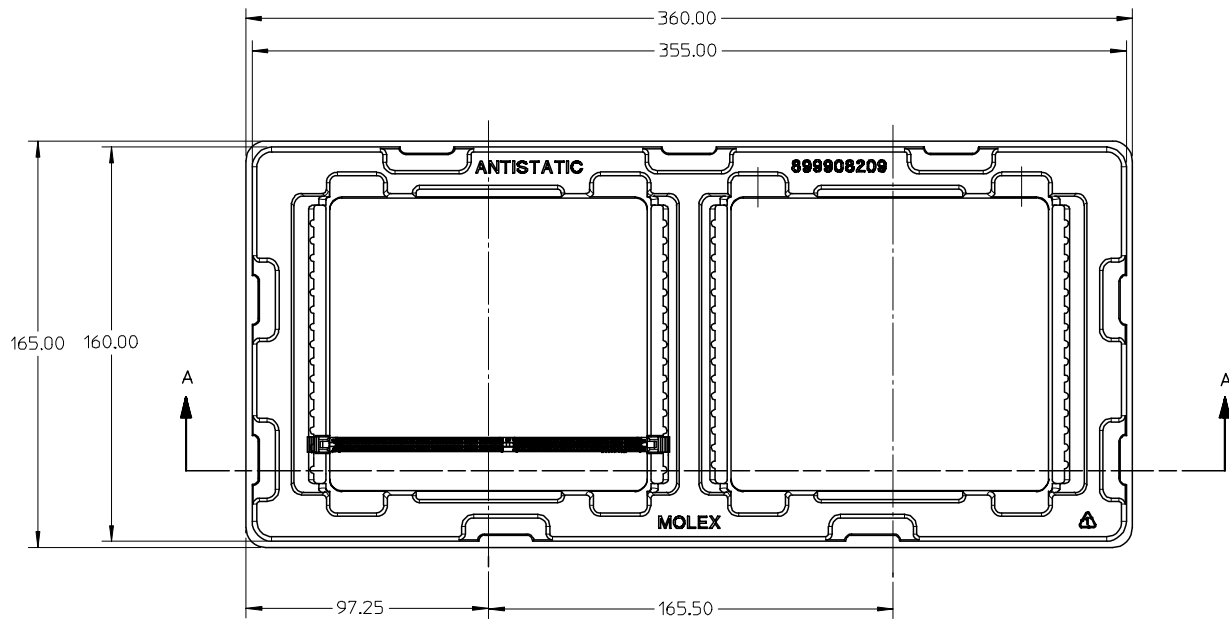
B

A

A

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOUR
78061-0001	CENTER (1.8V)	2.67	1.57	0.38µM/15µIN MIN. GOLD ON CONTACT 2.54µM/100µIN MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27µM/50µIN MIN. NICKEL UNDERPLATE	NATURAL (OFF WHITE)
78061-0002		3.18	2.36		
78061-0011		2.67	1.57	0.76µM/30µIN MIN. GOLD ON CONTACT 2.54µM/100µIN MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27µM/50µIN MIN. NICKEL UNDERPLATE	
78061-0012		3.18	2.36		
78061-0051		2.67	1.57	0.38µM/15µIN MIN. GOLD ON CONTACT 2.54µM/100µIN MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27µM/50µIN MIN. NICKEL UNDERPLATE	BLACK
78061-0052		3.18	2.36		
78061-0061		2.67	1.57	0.76µM/30µIN MIN. GOLD ON CONTACT 2.54µM/100µIN MIN. PURE TIN (MATTE) ON SOLDERTAILS 1.27µM/50µIN MIN. NICKEL UNDERPLATE	
78061-0062		3.18	2.36		

TRAY DWG ADDED EC NO: S2007-0602 DRWN:CMTEO CHKD:SHLENI APPR:GGLLEE	2006/12/26 2006/12/26 2006/12/28	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			$\nabla = 0$ $\triangle = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	FB DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H
			DRAWN BY: JTAN CHECKED BY: SRRAMESH APPROVED BY: GGLEE	DATE: 2005/10/20 DATE: 2005/12/05 DATE: 2005/12/06	TITLE:	MOLEX INCORPORATED		
			MATERIAL NO.	SEE TABLE	DOCUMENT NO. SD-78061-001	SHEET NO. 4 OF 5		



NOTES:
1. CAVITY QTY: 2 X 15 = 30 PCS

TRAY DWG ADDED	2006/12/26
EC NO: S2007-0602	2006/12/26
DRWN:CMTEO	2006/12/26
CHKD:SHLENI	2006/12/26
APPR:GGLLEE	2006/12/26
REV	DESCRIPTION
A4	

QUALITY SYMBOLS	$\nabla=0$
	$\nabla C=0$

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm
4 PLACES	\pm ---
3 PLACES	\pm ---
2 PLACES	\pm 0.2
1 PLACE	\pm ---
ANGULAR \pm 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
JTAN	2005/10/20
CHECKED BY	DATE
SRRAMESH	2005/12/05
APPROVED BY	DATE
GGLLEE	2005/12/06
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE	NTS	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
TITLE		FB DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
MOLEX INCORPORATED		MOLEX INCORPORATED		
DOCUMENT NO.		SD-78061-001		SHEET NO. 5 OF 5
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